



Lead Free No-clean Solder Paste

S3X58-M406D

■ Feature

- 1) A combination of binary eutectic alloy composed of Tin and Silver, and Koki's unique halide free no-clean flux realizes soldering performances equivalent to conventional no-clean solder pastes including wettability.
- 2) Carefully selected flux chemistry ensures unique low voids formation and powerful wetting.
- 3) Specially developed flux system ensures both extremely high reliability and superior solder wettability.
- 4) Extremely long tack time offers wide process window.
- 5) Low color flux residue offers superior cosmetic appearance.

■ Specifications

| Application | | Dispensing | |
|-------------------------|---|--------------------------|----------------------|
| Products | | S3X58-M406D | |
| Alloy | Composition (%) | Sn3Ag0.5Cu | |
| | Shape | Spherical | |
| | Particle size (μm) | 20 – 38 | |
| | Melting point (°C) | 217 - 218 | |
| Flux | Halide content (%) | 0.0 | |
| | Surface insulation resistance * ¹ | Initial value (Ω) | $> 1 \times 10^{13}$ |
| | | After humidification (Ω) | $> 1 \times 10^{11}$ |
| | Aqueous solution resistivity* ² (Ω cm) | $> 5 \times 10^4$ | |
| Flux type | ROL0 | | |
| Product | Flux content (%) | 13 | |
| | Viscosity* ³ (Pa.S) | 120 | |
| | Copper plate corrosion* ⁴ | Passed | |
| | Solder spread factor (%) | > 85 | |
| | Tack time | > 24 hours | |
| Shelf life (below 10°C) | 6 months | | |

1. SIR40°C × 90%RH × 96Hr
2. Aqueous solution resistivityIn accordance with MIL specifications.
3. ViscosityMalcom spiral type viscometer, PCU-2 at 25°C 10rpm
4. Copper plate corrosionIn accordance with JIS.

*Specifications are subject to change